



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Nobuaki HASHIMOTO

Application No.: 09/615,503

Filed: July 13, 2000

For: SEMICONDUCTOR DEVICE, METHOD OF FABRICATING THE SAME, CIRCUIT BOARD, AND ELECTRONIC APPARATUS

Group Art Unit: 2823

Examiner: D. Collins

Docket No.: 101929.02

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AMENDMENT UNDER 37 C.F.R. §1.111

Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

In reply to the Office Action dated January 24, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claims 1, 2, 7, 8, 9, 11, 13, 14, 15, 16 and 17 as follows:

1. (Amended) A method of fabricating a semiconductor device comprising:

- (a) attaching a plurality of semiconductor chips to a tape;
  - (b) cutting the tape to obtain substrates; and
  - (c) providing a plurality of external terminals on each of the substrates,
- wherein the steps (a) and (b) are carried out in a reel-to-reel transport system.

2. (Amended) The method of fabricating a semiconductor device as defined in claim 1, further comprising:

attaching a reinforcing member to the tape in positions corresponding to each of the semiconductor chips, before the step (b).